

ABSTRACT

The changes in depth distributions of atomic compositions in the structures of TiO₂/SiO₂/Si after ion implantation was investigated. The samples were implanted with Ne⁺, Ar⁺, Kr⁺ and Xe⁺ ions at difference energy 100, 150, 200 and 250 keV. Depth profiles of elements in the samples were analyzed by the Rutherford Backscattering Spectrometry (RBS) method [1]. It was found that the mixed layers existed between TiO₂/SiO₂ interface after ion irradiation. The thickness of transition layers increased with growing of ion energy.

EXPERIMENT

❖ Ion implantation.

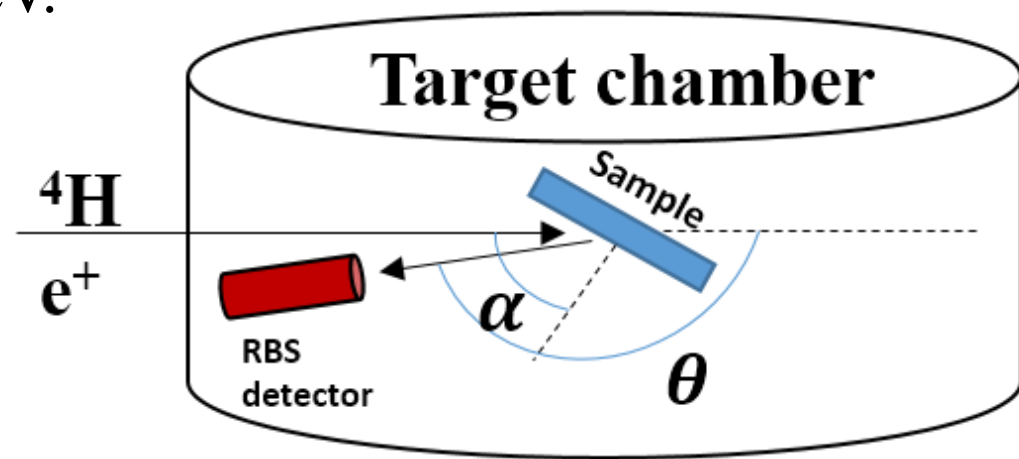
The samples irradiated with 4 different ion specimens Ne⁺, Ar⁺, Kr⁺ and Xe⁺ at different energy 100, 150, 200 and 250 keV. The samples have been irradiated with the ions at the same fluency 3*10¹⁶ (ions/cm²) [2].

❖ Analytical method

- The energy of He⁺ ion beam: 1.5 MeV.
- The incident angle $\alpha = 60^\circ$
- Scattering angle $\theta = 170^\circ$
- Depth profile were calculated using SIMNRA code [3].
- Detector energy resolution 15 keV

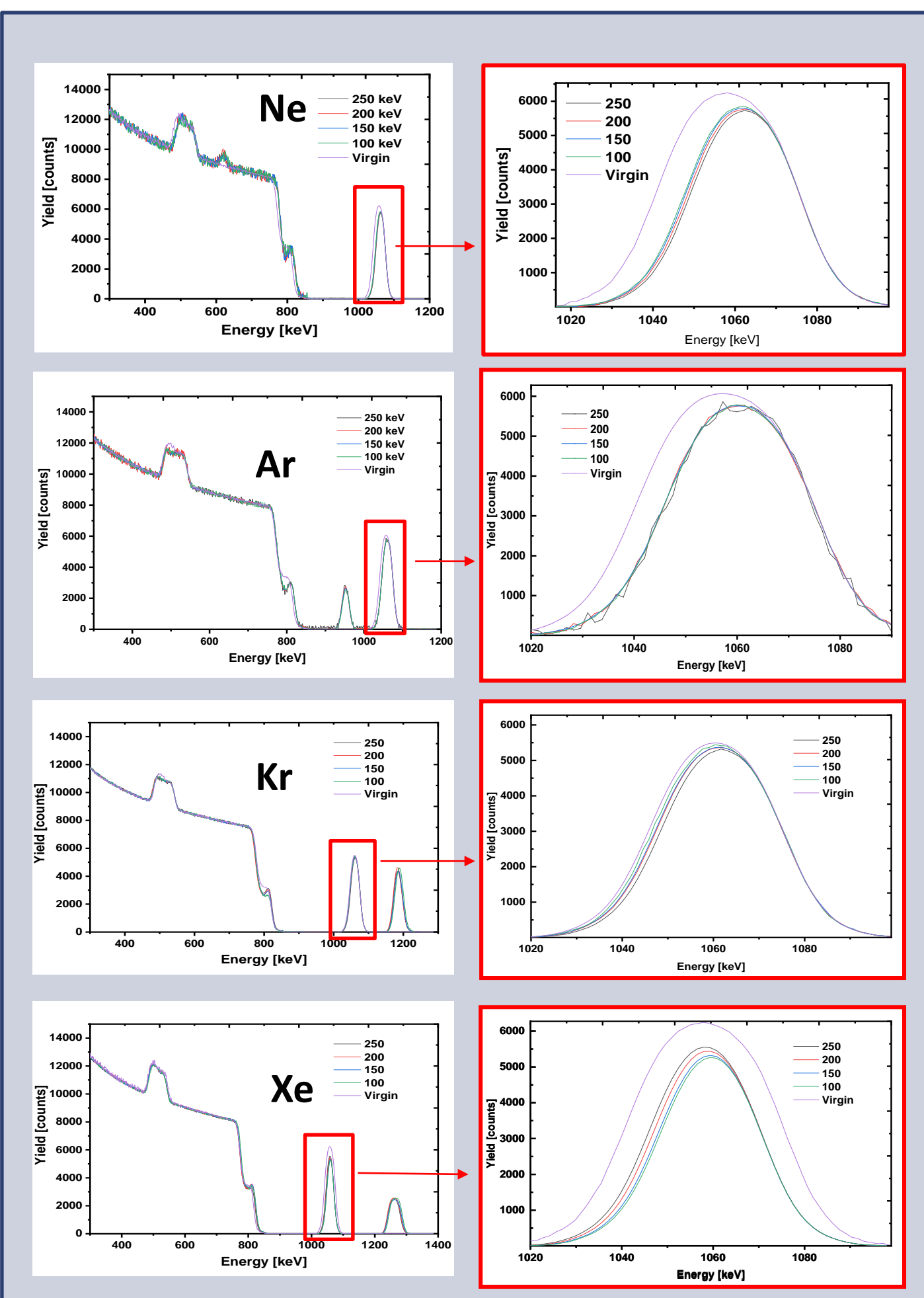
❖ Theoretical calculation

Depth-dependent damage and defect concentration profiles were calculated for understanding and explanation the obtained effects using the Stopping and Range of Ions in Matter (SRIM)-2008 [4].

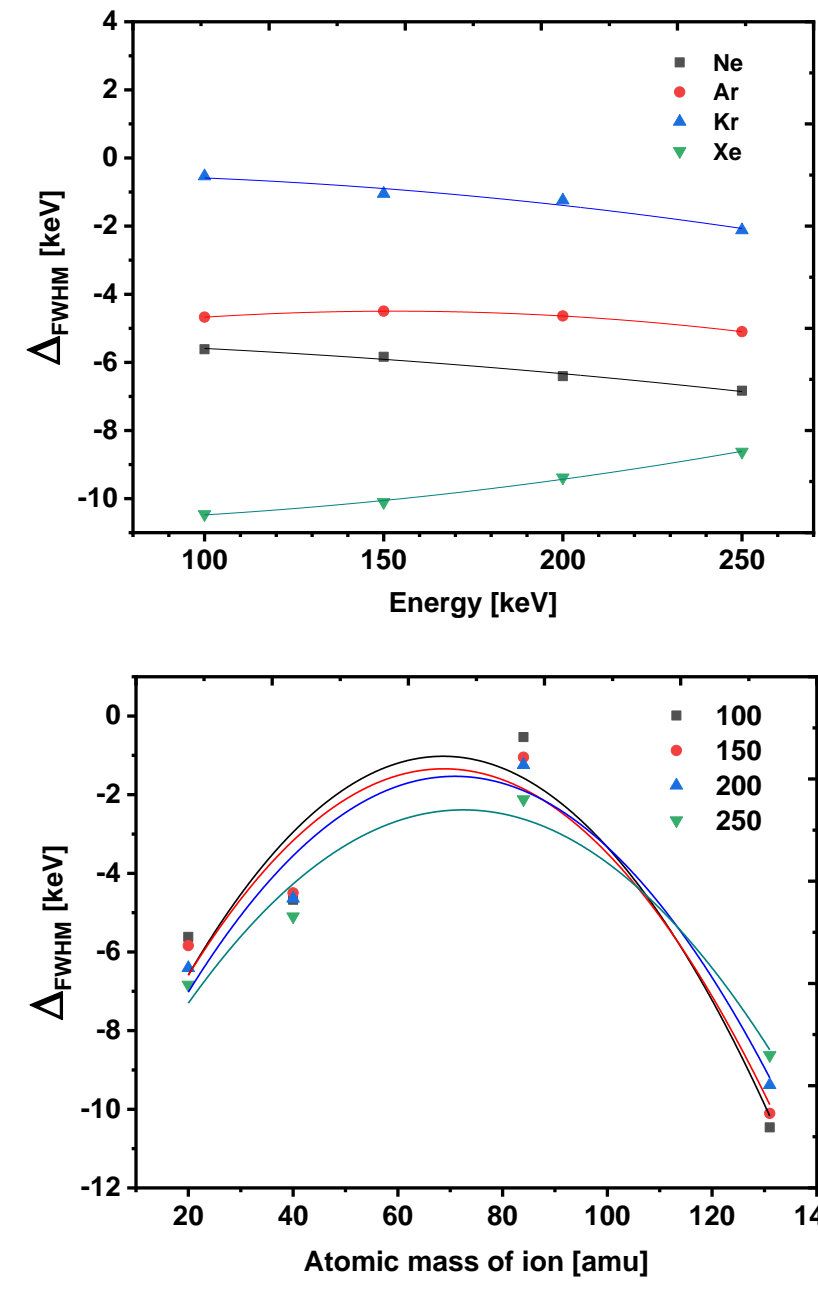
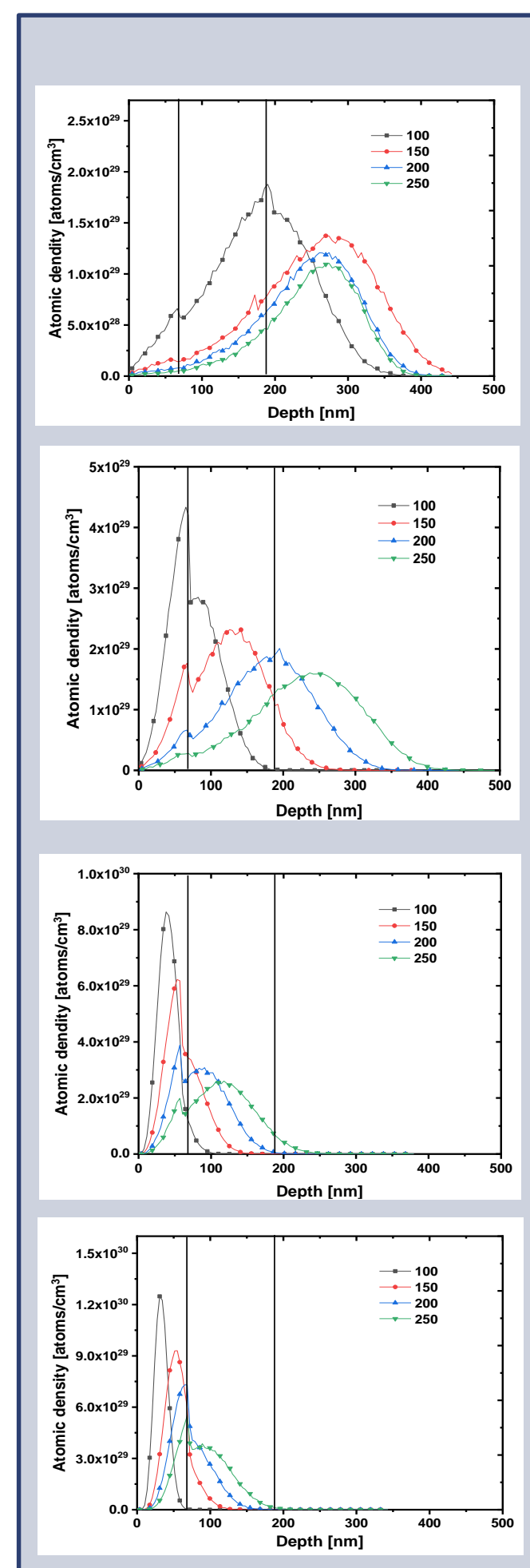


RESULTS

RBS spectra for samples before and after implanted with ions at different energies



The projected range of ions at different energies in TiO₂/SiO₂ samples (SRIM calculation)



The mixing in the samples is best characterized by an error function [5]:

$$C(x) = \frac{C_s}{2\sqrt{\pi Dt}} \exp\left[-\frac{(x-x_0)^2}{4Dt}\right]$$

where

$C(x)$ is the Ti atom concentration at location x , C_s is the initial Ti atom concentration, D is the effective diffusion coefficient and x_0 is the position of the initial Ti film.

$$D = \frac{\sigma^2 - \sigma_0^2}{2t} \left(\frac{\delta E}{[\epsilon_0]_{SiO_2} N_{SiO_2}} \right)^2$$

$$\Delta^2 = (\text{FWHM})^2 - (\text{FWHM})_0^2 = 2.34^2 (\sigma^2 - \sigma_0^2)$$

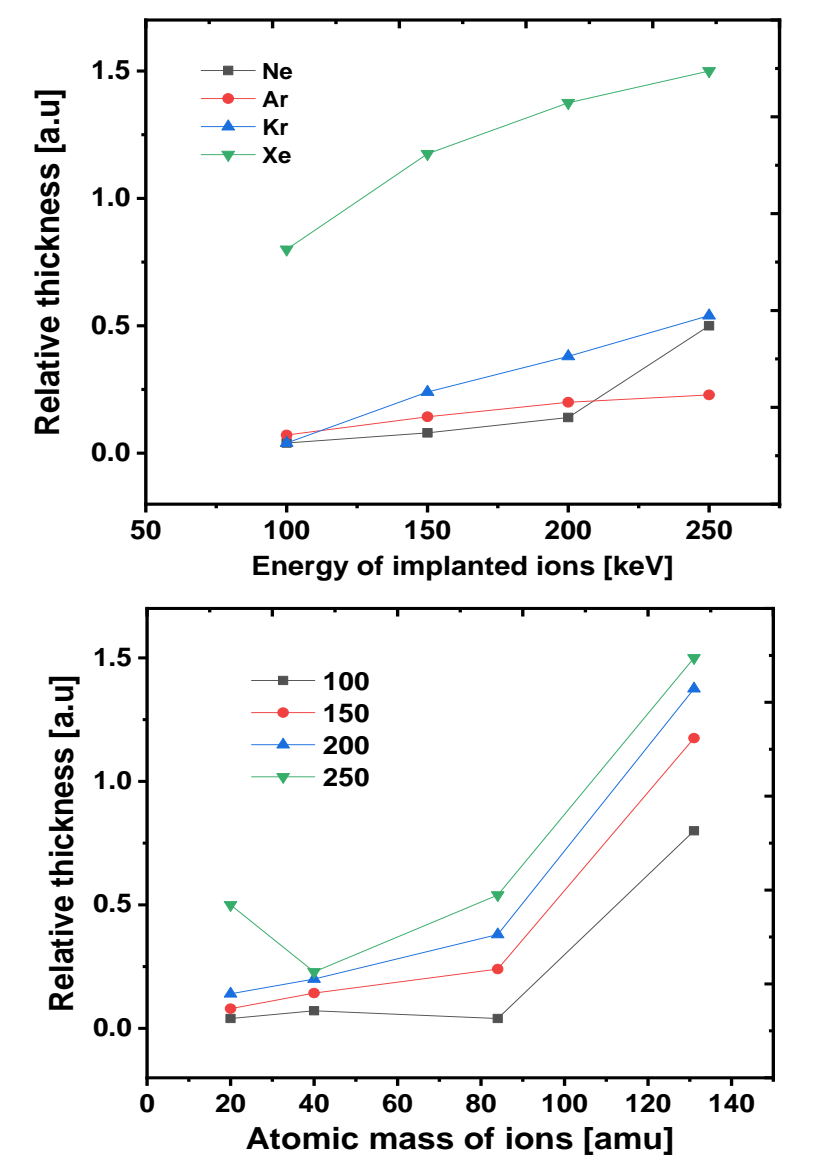
These equation implies that:

$$D \propto \Delta$$

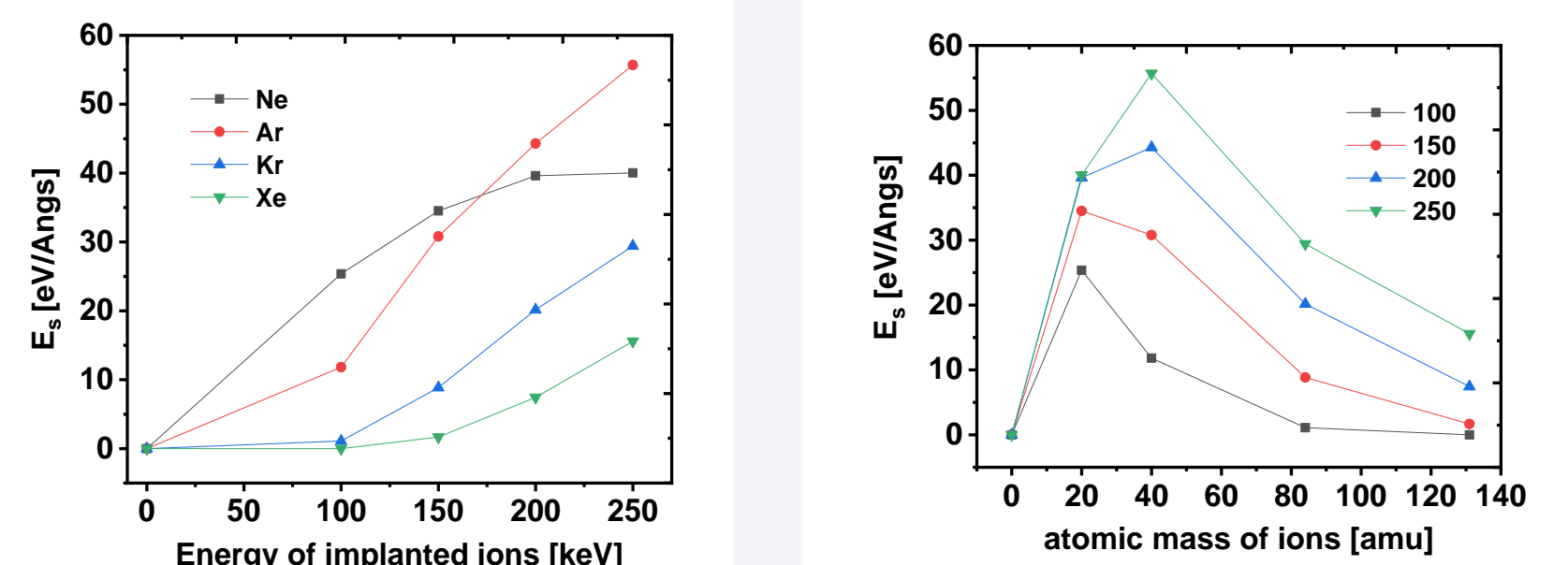
The relative changing thickness of the transition layers before and after ion

$$r_t = \frac{t_{im} - t_{vir}}{t_{vir}}$$

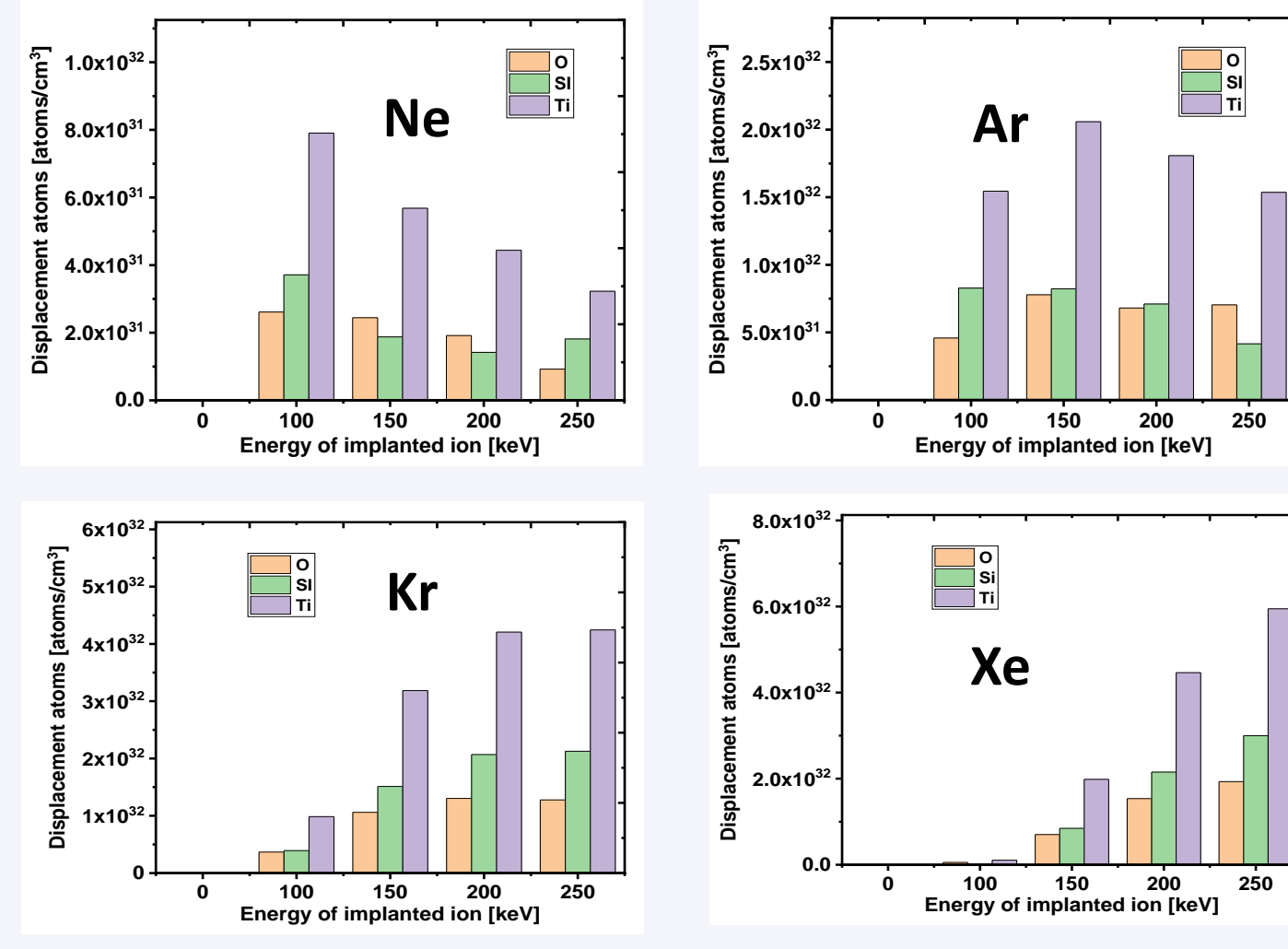
Where r_t is the relative changing thickness of the transition layers, t_{im} is thickness of the transition layers in samples after implantation, t_{vir} is thickness of the transition layers in virgin samples - before implantation.



The energy loss of ions in the TiO₂/SiO₂ transition layers



The displacements atoms in TiO₂/SiO₂ transition layers



REFERENCE

- [1] W.K. Chu, J.W. Mayer, M.A. Nicolet, Backscattering Spectrometry, Academic Press, New York San Francisco London, 1978.
- [2] M. Turek, S. Przenal, A. Drozdziel, K. Pysznik, Versatile plasma ion source with an internal evaporator, Nucl. Instrum. Methods Phys. Res. B, 269, 7, (2011), 700-707.
- [3] M. Mayer, SIMNRA User's Guide, Report IPP 9/113, Max-Planck-Institut für Plasmaphysik, Garching, Germany, 1997.
- [4] J.F. Ziegler, J.P. Biersack and M.D. Ziegler, SRIM-The Stopping and Range of Ions in Matter, SRIM Co, Ion Implantation Press, Chester, 2008.
- [5] M. G. Scott and R. A. Collins, G. Deamaley, Radiation Enhanced Diffusion in Kr⁺ bombarded Ni-Yb films, Radiafion Efects, 1984, Vol. 81, Pp. 211-219.

CONCLUSIONS

- Thickness of the transition layers increase with growing energy of implanted ions.
- Speed of increasing the thickness of mixed layers depends on ions mass.
- For the cases of Kr⁺ and Ar⁺ ion irradiation, thickness of transition layers increase as a linear function of ion energy.